No. F181201

ABLIC Inc.

563, Takatsukashinden, Matsudo-shi,
Chiba 270-2222, Japan
Phone: (+81)47-391-2020 / Fax: (+81)47-391-7500

December 10, 2018

Change Notification: Material change of solder plating on outer leads for SNT/HSNT package (Sn-Bi --> Sn 100%)

Dear Customers,

We would like to inform you that as of the end of march, 2019, we will implement the material change of solder plating on outer leads for SNT/HSNT package.

[Change item]

Before change	After change
Outer Leads of solder plating: Sn-Bi (bismuth)	Outer leads of solder plating: Sn 100%

* The reflow profile for mounting on a board is not changed.

* The product names are not changed.

[Product]

The last character of product name(an environmental code): G or S

[Package type]

SNT/HSNT

[Effective date]

The end of march, 2019

[Quality]

All the products after the change comply with our reliability standards.

[Reason for change]

ABLIC Inc. has been promoting to adopt Sn 100% for the material of outer leads of our all products considering environmental effect. Thanks to our customers, we have achieved to replace 94 % of all the Sn-Bi packages containing Bi(bismuth) with those consisting of Sn 100%.

Bi free products have been indispensable in Europe and America, which are taking the global environment into consideration these days. One of the reasons is that Bi is extracted as bi-product when refining Pb(lead). Although the amount of Pb in Sn-Bi solder plating meets the criteria regulated by RoHS Directive, it contains a slightly small amount of Pb. Therefore, we would like to promote to replace our SNT/HSNT package products containing Sn-Bi, which are used for small mobile devices, with those containing Sn 100% so that we can deal with the global situation moreover.

We appreciate your fully understanding and cooperation to achieve those activities.

Sincerely,

Masahisa Uramoto
General Manager
Quality Assurance Department
ABLIC Inc.